



HIGH SPEED MICRO CARD

PCIE, SAL1 SERIES

Mates with:
.062" (1,60mm) Card

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?PCIE

Insulator Material: Black Nylon

Contact: Phosphor Bronze

Plating: Au or Sn over 50µ" (1,27µm) Ni

Current Rating: Testing Now!

Operating Temp: -55°C to +125°C

Card Insertion Depth: (8,00mm) .315" nominal

RoHS Compliant: Yes

Processing:

Max Processing Temp: 230°C for 60 seconds

Lead-Free Solderable: Wave only

Note: Some lengths, styles and options are non-standard, non-returnable.



PCIE

NO. OF POSITIONS

02

PLATING OPTION

D

TERMINATION

-036, -064, -098, -164

-F
= Gold flash on contact, Tin on tail

-EM2
= Edge Mount

-TH
= Through-hole

Dimensions: (11,00) .433, (15,40) .606, (2,05) .081DIA, (1,35) .053, (10,00) .394, (3,10) .122, (2,50) .098, (2,00) .079, (7,50) .295, (10,10) .398, (4,20) .165, (3,00) .118

Dimensions: (861) .339, (870) .343, (3,97) .156, (1,50) .059

Dimensions: (1,00) .03937, (1,78) .070, (11,65) .459

POSITIONS	A	B	C
-036 (X1)	(25,00) .984	(7,65) .301	(9,15) .360
-064 (X4)	(39,00) 1.535	(21,65) .852	(23,15) .911
-098 (X8)	(56,00) 2.205	(38,65) 1.522	(40,15) 1.581
-164 (X16)	(89,00) 3.504	(71,65) 2.821	(73,15) 2.880

Mates with:
(1,60mm) .062" or
(2,40mm) .093" card

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SAL1

Insulator Material: Black LCP

Contact Material: BeCu

Plating: Au or Sn over 50µ" (1,27µm) Ni

Operating Temp: -55°C to +125°C

Current Rating: 2.3 A @ 80°C

RoHS Compliant: Yes

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,10mm) .004" max

Note: Some lengths, styles and options are non-standard, non-returnable.



SAL1

NO. OF POSITIONS

01

PLATING OPTION

S

A

20, 27, 30, 40

-S
= 30µ" (0,76µm) Gold on contact, Matte Tin on tail

APPLICATION SPECIFIC OPTION
Heavy Gold plating available. Call Samtec.

Dimensions: (5,45) .215, (1,50) .059, (6,16) .243, (2,10) .083

Dimensions: (1,90) .075, (1,20) .047 DIA

Dimensions: (0,25) .010, (6,16) .243, (2,10) .083

1.65mm Stack Height	Rated @ -3dB Insertion Loss
Single-Ended Signaling	8.5 GHz / 17 Gbps
Differential Pair Signaling	9.0 GHz / 18 Gbps

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM